



DOCUMENT TYPE: PLP

DOCUMENT ID #: 90-100263

REVISION: A-000

DOCUMENT TITLE: PACKAGE LAND PATTERN, [T1633CNY+4C] TQFN

EFFECTIVE DATE: 02/07/2024

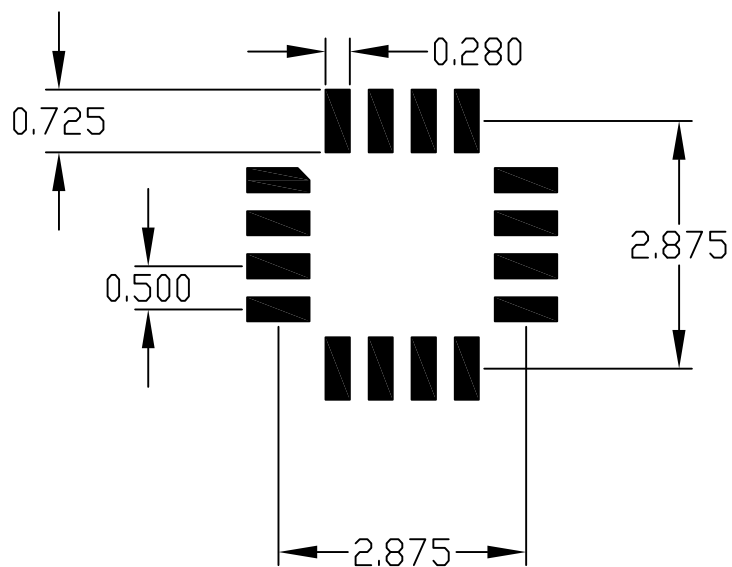
EXPIRATION DATE:

CHANGE NUMBER: 1203880

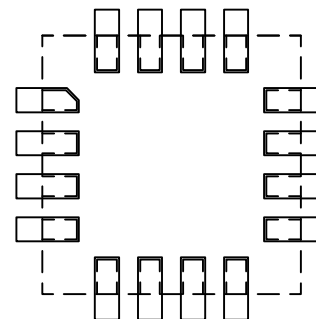
ORIGINATOR: Aurelio Giron Jr.

REASON FOR CHANGE:
INITIAL RELEASE

RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100748
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, PbFREE PACKAGES.
5. ALL DIMENSIONS IN MM.

—DRAWING NOT TO SCALE—



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depends on many factors unknown to Analog Devices Inc. (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice.

Contact technical support at <https://www.analog.com/en/support> for further questions.

TITLE:

PACKAGE LAND PATTERN,
[T1633CNY+4C] TQFN

APPROVAL

CHUCK XIA

DOCUMENT CONTROL NO.

90-100263

REV.

A

1

1

